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May 20th, 2025

PCN EIC-1150 Additional Epoxy Mold Compound Qualification for selected 8L DIP and SMT package type devices

Detailed Description of Change

Littelfuse IXYS Integrated Circuits Division (ICD) would like to inform you about the qualification of an additional EMC (Epoxy Mold Compound) to ensure security of supply for the part numbers summarized in the table below.

The affected part numbers listed below are fully qualified in accordance with established performance and reliability criteria.

Part number
CPC1302G
CPC1302GS
CPC1302GSTR
FDA217
FDA217S
FDA217STR
LBA716
LBA716S
LBA716STR
PAA140
PAA140S
PAA140STR
PBA150
PBA150S
PBA150STR

Form, fit, function changes: None Part number changes: None Replacement products: N/A

Last time buy: N/A

Effective date: Immediately





The PCN number assigned to this action is **PCN EIC-1150** and must be referenced in any correspondence related to the change.

If you have any other questions or concerns, please contact your local Littelfuse sales representative or Product Manager below for further assistance.

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